

# Frequency Multiplier and Zero Delay Buffer

#### **Features**

- 90 ps typical jitter OUT2
- 200 ps typical jitter OUT1
- 65 ps typical output-to-output skew
- 90 ps typical propagation delay
- Voltage range: 3.3 V ± 5%, or 5 V ± 10%
- Output frequency range: 5 MHz to 133 MHz
- Two outputs
- Configuration options allow various multiplications of the reference frequency refer to Configuration Options to determine the specific option which meets your multiplication needs
- Available in 8-pin SOIC package

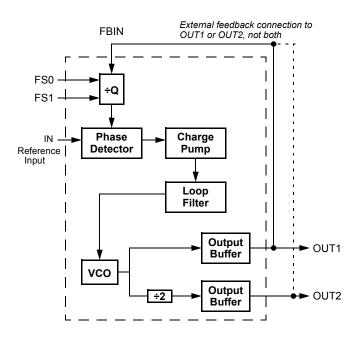
#### **Configuration Options**

FBIN	FS0	FS1	OUT1	OUT2
OUT1	0	0	2 × REF	REF
OUT1	1	0	4 × REF	2 × REF
OUT1	0	1	REF	REF/2
OUT1	1	1	8 × REF	4 × REF
OUT2	0	0	4 × REF	2 × REF
OUT2	1	0	8 × REF	4 × REF
OUT2	0	1	2 × REF	REF
OUT2	1	1	16 × REF	8 × REF

### **Functional Description**

For a complete list of related documentation, click here.

### **Logic Block Diagram**





#### **Contents**

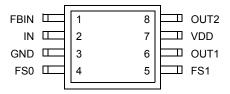
Pinouts	3
Pin Definitions	3
Functional Overview	4
How to Implement Zero Delay	4
Inserting Other Devices in Feedback Path	4
Phase Alignment	4
Absolute Maximum Ratings	5
DC Electrical Characteristics	5
DC Electrical Characteristics	5
Thermal Resistance	5
AC Electrical Characteristics	6
AC Electrical Characteristics	7
Ordering Information	8
Ordering Code Definitions	

Package Diagram	5
Acronyms	10
Document Conventions	10
Units of Measure	10
Document History Page	<b>1</b> 1
Sales, Solutions, and Legal Information	12
Worldwide Sales and Design Support	12
Products	
PSoC® Solutions	12
Cypress Developer Community	12
Technical Support	12



# **Pinouts**

Figure 1. 8-pin SOIC pinout



# **Pin Definitions**

Pin Name	Pin No.	Pin Type	Pin Description	
IN	2	I	Reference Input: The output signals are synchronized to this signal.	
FBIN	1	I	Feedback Input: This input must be fed by one of the outputs (OUT1 or OUT2) to ensure proper functionality. If the trace between FBIN and the output pin being used for feedback is equal in length to the traces between the outputs and the signal destinations, then the signals received at the destinations are synchronized to the REF signal input (IN).	
OUT1	6	0	Output 1: The frequency of the signal provided by this pin is determined by the feedback signal connected to FBIN, and the FS0:1 inputs (see Configuration Options on page 1).	
OUT2	8	0	Output 2: The frequency of the signal provided by this pin is one-half of the frequency of OUT1. See Configuration Options on page 1.	
VDD	7	Р	Power Connections: Connect to 3.3 V or 5 V. This pin should be bypassed with a $0.1-\mu F$ decoupling capacitor. Use ferrite beads to help reduce noise for optimal jitter performance.	
GND	3	Р	round Connection: Connect all grounds to the common system ground plane.	
FS0:1	4, 5	I	Function Select Inputs: Tie to $V_{DD}$ (HIGH, 1) or GND (LOW, 0) as desired per Configuration Options on page 1.	



#### **Functional Overview**

The CY2302 is a two-output zero delay buffer and frequency multiplier. It provides an external feedback path allowing maximum flexibility when implementing the Zero Delay feature. This is explained further in the sections of this datasheet titled, How to Implement Zero Delay, and Inserting Other Devices in Feedback Path.

The CY2302 is a pin-compatible upgrade of the Cypress W42C70-01. The CY2302 addresses some application dependent problems experienced by users of the older device.

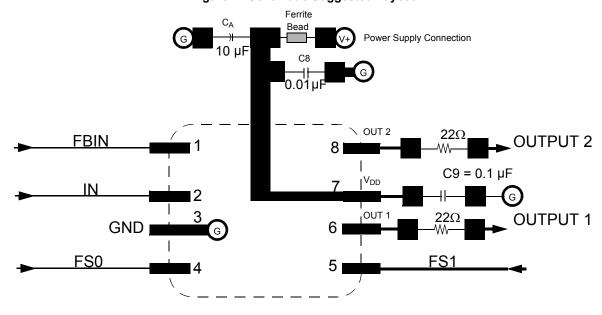


Figure 2. Schematic/Suggested Layout

#### How to Implement Zero Delay

Typically, Zero Delay Buffers (ZDBs) are used because a designer wants to provide multiple copies of a clock signal in phase with each other. The whole concept behind ZDBs is that the signals at the destination chips are all going HIGH at the same time as the input to the ZDB. In order to achieve this, layout must compensate for trace length between the ZDB and the target devices. The method of compensation is described as follows

External feedback is the trait that allows for this compensation. The PLL on the ZDB causes the feedback signal to be in phase with the reference signal. When laying out the board, match the trace lengths between the output being used for feedback and the FBIN input to the PLL.

If it is desirable to either add a little delay, or slightly precede the input signal, this may also be implemented by either making the trace to the FBIN pin a little shorter or a little longer than the traces to the devices being clocked.

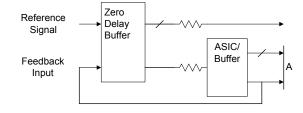
#### **Inserting Other Devices in Feedback Path**

Another nice feature available due to the external feedback is the ability to synchronize signals to the signal coming from some other device. This implementation can be applied to any device (ASIC, multiple output clock buffer/driver, etc.) that is put into the feedback path.

Referring to Figure 2, if the traces between the ASIC/Buffer and the destination of the clock signal(s) (A) are equal in length to the

trace between the buffer and the FBIN pin, the signals at the destination(s) device is driven HIGH at the same time when the Reference clock provided to the ZDB goes HIGH. Synchronizing the other outputs of the ZDB to the outputs from the ASIC/Buffer is more complex however, as any propagation delay from the ZDB output to the ASIC/Buffer output must be accounted for.

Figure 3. Six Output Buffer in the Feedback Path



#### **Phase Alignment**

In cases where OUT1 (i.e., the higher frequency output) is connected to FBIN input pin the output OUT2 rising edges may be either 0 or 180° phase aligned to the IN input waveform (as set randomly when the input and/or power is supplied). If OUT2 is desired to be rising-edge aligned to the IN input's rising edge, then connect the OUT2 (i.e., the lowest frequency output) to the FBIN pin. This set-up provides a consistent input-output phase relationship.



# **Absolute Maximum Ratings**

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Parameter	Description		Unit
$V_{DD}$ , $V_{IN}$	Voltage on any pin with respect to GND		V
T <sub>STG</sub>	Storage temperature		°C
T <sub>A</sub>	Ambient operating temperature, commercial	0 to +70	°C
	Ambient operating temperature, industrial	-40 to +85	°C
T <sub>B</sub>	Ambient temperature under bias	-55 to +125	°C
$P_{D}$	Power dissipation	0.5	W

#### **DC Electrical Characteristics**

 $T_A$  = 0 °C to 70 °C or –40 °C to 85 °C,  $V_{DD}$  = 3.3 V ± 5%

Parameter	Description	Test Condition	Min	Тур	Max	Unit
$I_{DD}$	Supply current	Unloaded, 100 MHz	-	17	35	mA
$V_{IL}$	Input low voltage	_	-	-	0.8	V
V <sub>IH</sub>	Input high voltage	_	2.0	-	-	V
V <sub>OL</sub>	Output low voltage	I <sub>OL</sub> = 12 mA	-	-	0.4	V
V <sub>OH</sub>	Output high voltage	I <sub>OH</sub> = –12 mA	2.4	-	-	V
I <sub>IL</sub>	Input low current	V <sub>IN</sub> = 0V	-40	-	5	μА
I <sub>IH</sub>	Input high current	$V_{IN} = V_{DD}$	_	_	5	μΑ

#### **DC Electrical Characteristics**

 $T_A$  = 0 °C to 70 °C or –40 °C to 85 °C,  $V_{DD}$  = 5 V ± 10%

Parameter	Description	Test Condition	Min	Тур	Max	Unit
I <sub>DD</sub>	Supply current	Unloaded, 100 MHz	_	37	50	mA
V <sub>IL</sub>	Input low voltage	_	_	-	0.8	V
V <sub>IH</sub>	Input high voltage	-	2.0	-	_	V
V <sub>OL</sub>	Output low voltage	I <sub>OL</sub> = 12 mA	_	-	0.4	V
V <sub>OH</sub>	Output high voltage	I <sub>OH</sub> = –12 mA	2.4	-	_	V
I <sub>IL</sub>	Input low current	V <sub>IN</sub> = 0 V	-80	-	5	μА
I <sub>IH</sub>	Input high current	$V_{IN} = V_{DD}$	_	-	5	μА

#### **Thermal Resistance**

Parameter [1]	Description	Test Conditions	8-pin SOIC	Unit
$\theta_{JA}$	0	Test conditions follow standard test methods and procedures for measuring thermal impedance, in	132	°C/W
$\theta_{JC}$	Thermal resistance (junction to case)	accordance with EIA/JESD51.	43	°C/W

#### Note

Document Number: 38-07154 Rev. \*I Page 5 of 12

<sup>1.</sup> These parameters are guaranteed by design and are not tested.



#### **AC Electrical Characteristics**

 $T_A$  = 0 °C to +70 °C or –40 °C to 85 °C,  $V_{DD}$  = 3.3 V  $\pm$  5%  $^{[2]}$ 

Parameter	Description	Test Condition	Min	Тур	Max	Unit
f <sub>IN</sub>	Input Frequency [3]	_	5	_	133	MHz
f <sub>OUT</sub>	Output Frequency	OUT1 15 pF load	10	_	133	MHz
t <sub>R</sub>	Output Rise Time	0.8 V to 2.0 V, 15 pF load	_	-	3.5	ns
t <sub>F</sub>	Output Fall Time	2.0 V to 0.8 V, 15 pF load	_	-	2.5	ns
t <sub>ICLKR</sub>	Input Clock Rise Time [4]		_	_	10	ns
t <sub>ICLKF</sub>	Input Clock Fall Time [4]		_	_	10	ns
t <sub>D</sub>	Duty Cycle	15-pF load <sup>[5]</sup>	40	50	60	%
t <sub>LOCK</sub>	PLL Lock Time	Power supply stable	_	_	1.0	ms
t <sub>JC</sub>	Jitter, Cycle-to-Cycle	OUT1, f <sub>OUT</sub> >30 MHz	_	200	300	ps
		OUT2, f <sub>OUT</sub> >30 MHz	_	90	300	ps
t <sub>DC</sub>	Die Out Time <sup>[6]</sup>	-	100	_	_	Clock Cycles
t <sub>SKEW</sub>	Output-output Skew <sup>[7]</sup>	_	_	65	250	ps
t <sub>PD</sub>	Propagation Delay <sup>[7]</sup>	_	-350	90	350	ps

- All AC specifications are measured with a 50Ω transmission line, load terminated with 50 Ω to 1.4 V.
   Input frequency is limited by output frequency range and input to output frequency multiplication factor (which is determined by circuit configuration).
   Longer input rise and fall time degrades skew and jitter performance.
- 5. Duty cycle is measured at 1.4 V.
- 6. 33 MHz reference input suddenly stopped (0 MHz). Number of cycles provided prior to output falling to <16 MHz.
- 7. Skew is measured at 1.4 V on rising edges.



#### **AC Electrical Characteristics**

 $T_A$  = 0 °C to +70 °C or –40 °C to 85 °C,  $V_{DD}$  = 5.0 V ± 10% <sup>[8]</sup>

Parameter	Description	Test Condition	Min	Тур	Max	Unit
f <sub>IN</sub>	Input Frequency [9]	-	5	-	133	MHz
f <sub>OUT</sub>	Output Frequency	OUT1 15 pF load	10	_	133	MHz
t <sub>R</sub>	Output Rise Time	0.8 V to 2.0 V, 15 pF load	_	-	2.5	ns
t <sub>F</sub>	Output Fall Time	2.0 V to 0.8 V, 15 pF load	_	-	1.5	ns
t <sub>ICLKR</sub>	Input Clock Rise Time [10]	-	_	-	10	ns
t <sub>ICLKF</sub>	Input Clock Fall Time [10]	-	_	_	10	ns
t <sub>D</sub>	Duty Cycle	15-pF load <sup>[11, 12]</sup>	40	50	60	%
t <sub>LOCK</sub>	PLL Lock Time	Power supply stable	_	-	1.0	ms
t <sub>JC</sub>	Jitter, Cycle-to-Cycle	OUT1, f <sub>OUT</sub> >30 MHz	_	200	300	ps
		OUT2, f <sub>OUT</sub> >30 MHz	_	90	300	ps
t <sub>DC</sub>	Die out time <sup>[13]</sup>	-	100	_	_	Clock cycles
t <sub>SKEW</sub>	Output-output Skew [14]	-	_	65	250	ps
t <sub>PD</sub>	Propagation Delay [14]	-	-350	90	350	ps

#### Notes

All AC specifications are measured with a 50Ω transmission line, load terminated with 50 Ω to 1.4 V.
 Input frequency is limited by output frequency range and input to output frequency multiplication factor (which is determined by circuit configuration).

<sup>10.</sup> Longer input rise and fall time degrades skew and jitter performance.

<sup>11.</sup> Duty cycle is measured at 1.4 V.

<sup>12.</sup> Duty Cycle measured at 120 MHz. For 133 MHz, degrades to 35/65 worst case.

<sup>13. 33</sup> MHz reference input suddenly stopped (0 MHz). Number of cycles provided prior to output falling to <16 MHz.

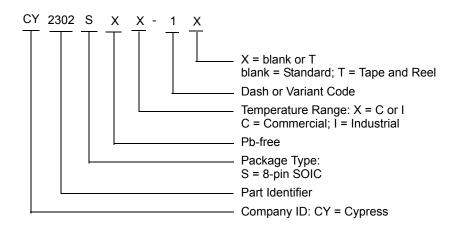
<sup>14.</sup> Skew is measured at 1.4 V on rising edges.



# **Ordering Information**

Ordering Code	Package Type	Temperature Grade
Pb-free		
CY2302SXC-1	8-pin SOIC	Commercial (0 °C to 70 °C)
CY2302SXC-1T	8-pin SOIC – Tape and Reel	Commercial (0 °C to 70 °C)
CY2302SXI-1	8-pin SOIC	Industrial (–40 °C to 85 °C)
CY2302SXI-1T	8-pin SOIC – Tape and Reel	Industrial (–40 °C to 85 °C)

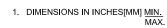
#### **Ordering Code Definitions**





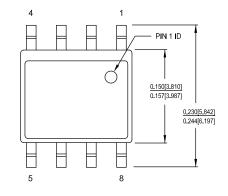
# **Package Diagram**

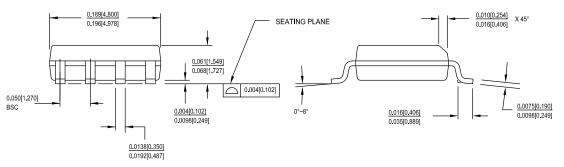
Figure 4. 8-pin SOIC (150 Mils) S0815/SZ815/SW815 Package Outline, 51-85066



- PIN 1 ID IS OPTIONAL,
   ROUND ON SINGLE LEADFRAME
   RECTANGULAR ON MATRIX LEADFRAME
- 3. REFERENCE JEDEC MS-012
- 4. PACKAGE WEIGHT 0.07gms







51-85066 \*H



# **Acronyms**

Acronym	Description
FBK	Feedback
PLL	Phase Locked Loop
MUX	Multiplexer

# **Document Conventions**

#### **Units of Measure**

Symbol	Unit of Measure	Symbol	Unit of Measure
°C	degree Celsius	μW	microwatt
dB	decibel	mA	milliampere
fC	femtocoulomb	mm	millimeter
fF	femtofarad	ms	millisecond
Hz	hertz	mV	millivolt
KB	1024 bytes	nA	nanoampere
Kbit	1024 bits	ns	nanosecond
kHz	kilohertz	nV	nanovolt
kΩ	kilohm	Ω	ohm
MHz	megahertz	ppm	parts per million
ΜΩ	megaohm	рА	picoampere
μΑ	microampere	pF	picofarad
μF	microfarad	рр	peak-to-peak
μH	microhenry	ps	picosecond
μs	microsecond	sps	samples per second
μV	microvolt	σ	sigma: one standard deviation
μVrms	microvolts root-mean-square		



# **Document History Page**

Document Title: CY2302, Frequency Multiplier and Zero Delay Buffer Document Number: 38-07154					
Revision	ECN	Orig. of Change	Submission Date	Description of Change	
**	110264	SZV	12/18/01	Change from Spec number: 38-00794 to 38-07154	
*A	394695	RGL	See ECN	Updated Features: Added typical char data. Updated Functional Overview: Added Phase Alignment. Updated AC Electrical Characteristics. Updated AC Electrical Characteristics. Updated Ordering Information: Updated part numbers.	
*B	2761988	KVM	09/10/09	Updated Absolute Maximum Ratings: Updated details in "Description" column corresponding to T <sub>A</sub> parameter. Updated Ordering Information: Updated part numbers. Updated details in "Temperature Grade" column (Added temperature values).	
*C	2894970	KVM	03/23/2010	Updated Ordering Information: Removed inactive parts. Updated Package Diagram.	
*D	2907904	KVM	04/08/2010	Updated Ordering Information: Removed inactive parts.	
*E	3204657	BASH	03/24/2011	Added Ordering Code Definitions under Ordering Information. Added Acronyms and Units of Measure.	
*F	4348705	CINM	04/16/2014	Updated Package Diagram: spec 51-85066 – Changed revision from *D to *F. Updated to new template. Completing Sunset Review.	
*G	4578443	AJU	11/25/2014	Updated Functional Description: Added "For a complete list of related documentation, click here." at the end.	
*H	5275750	PSR	05/18/2016	Added Thermal Resistance. Updated Package Diagram: spec 51-85066 – Changed revision from *F to *H. Updated to new template.	
*	5730303	TAVA	05/08/2017	Updated to new template. Completing Sunset Review.	



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Document Number: 38-07154 Rev. \*I Revised May 8, 2017 Page 12 of 12

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CD74HC4046AM CPLL66-2450-2450 NJM567D CY23S05SXI-1 STW81200T ADF4208BRUZ ADF4218LBRUZ ADF4355-3BCPZ
ADF5355BCPZ ADF4355BCPZ ADF4169WCCPZ ADF4360-7BCPZ ADF4360-6BCPZ ADF4360-5BCPZRL7 ADF4360-5BCPZRL7 ADF4360-5BCPZ
ADF4360-4BCPZRL7 ADF4360-4BCPZ ADF4360-3BCPZ ADF4360-2BCPZRL7 ADF4252BCPZ ADF4159CCPZ ADF4169CCPZ
ADF4252BCPZ-R7 ADF4360-0BCPZ ADF4360-1BCPZ ADF4360-1BCPZRL7 ADF4360-2BCPZ ADF4360-3BCPZRL7 ADF43607BCPZRL7 ADF4360-8BCPZ ADF4360-8BCPZRL7 ADF4360-9BCPZ ADF4360-9BCPZRL7 ADF4159CCPZ-RL7 ADF4159WCCPZ
ADF4360-0BCPZRL7 AD9901KPZ